Doc No. TT4-EA-12901

Revision. 3

Panasonic

MOS FET

MTM232230LBF

MTM232230LBF

Silicon N-channel MOS FET

For switching

■ Features

- Low drain-source On-state resistance : RDS(on) typ = 20 m Ω (VGS = 4.0 V)
- Low drive voltage: 2.5 V drive Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)
- Marking Symbol : BK

■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

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項目	記号	定格	単位				
Drain-source Voltage	VDS	20	V				
Gate-source Voltage	VGS	±10] v				
Drain current	ID	4.5	Α				
Peak drain current *1	IDp	18	Α				
Power dissipation *2	PD	500	mW				
Channel temperature	Tch	150	°C				
Operating ambient temperature	Topr	-40 to +85	°C				
Storage Temperature Range	Tstg	-55 to +150	°C				

- Note) *1 Pulse width \leq 10 μ s, Duty cycle \leq 1 %
 - *2 Measuring on ceramic board at $40 \times 38 \times 0.1$ mm Absolute maximum rating PD without heat sink shall be made 150 mW.

Unit: mm

2. 0

0. 15

(0. 65)(0. 65)

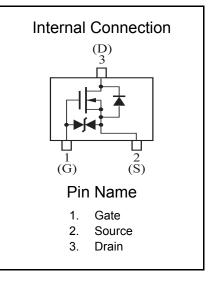
1. 3

1. Gate
2. Source
3. Drain

Panasonic SMini3-G1-B

JEITA SC-70

Code SOT-323



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■ Electrical Characteristics Ta = 25 °C ± 3 °C

項目	記号	条件	最小	標準	最大	単位
Drain-source surrender voltage	VDSS	ID = 1 mA, VGS = 0 V	20			V
Drain-source cutoff current	IDSS	VDS = 20 V, VGS = 0 V			1.0	μΑ
Gate-source cutoff current	IGSS	VGS = ±8 V, VDS = 0 V			±10	μΑ
Gate threshold voltage	Vth	ID = 1.0 mA, VDS = 10.0 V	0.4	0.85	1.3	V
Drain-source ON resistance *1	RDS(ON)1	ID = 1 A, VGS = 4 V		20	28	mΩ
	RDS(ON)2	ID = 0.6 A, VGS = 2.5 V		26	40	
Forward transfer admittance *1	Yfs	ID = 1 A, VDS = 10 V, f = 1 kHz	3.5			S
Short-circuit input capacitance (Common source)	Ciss			1 200		pF
Short-circuit output capacitance (Common source)	Coss	VDS = 10 V, VGS = 0, f = 1 MHz		85		
Reverse transfer capacitance (Common source)	Crss			80		
Turn-on Time *2	ton	VDD = 10 V, VGS = 0 to 4 V		16		ns
		ID = 1 A	10	10		115
Turn-off Time *2	toff	VDD = 10 V, VGS = 4 to 0 V		220		ns
		ID = 1 A		220		110

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

Established: 2010-12-15

Revised

: 2013-07-01

^{2. *1} Pulse test : Pulse width < 300 μs , Duty cycle < 2 %

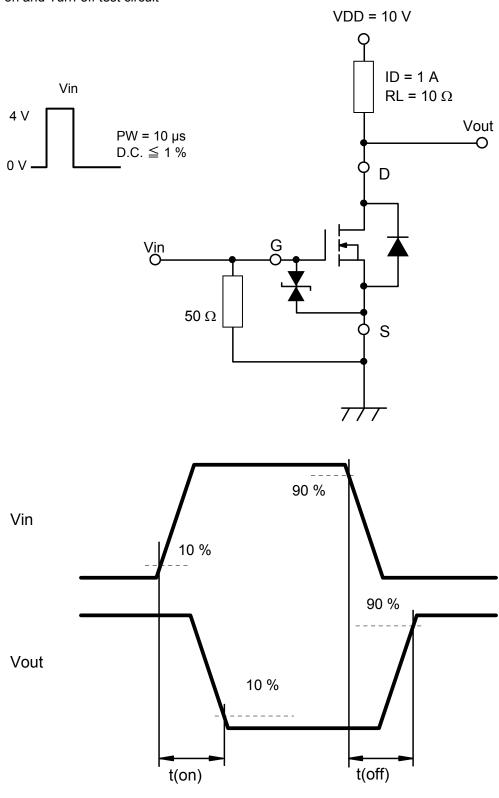
^{*2} Turn-on and Turn-off test circuit

MOS FET

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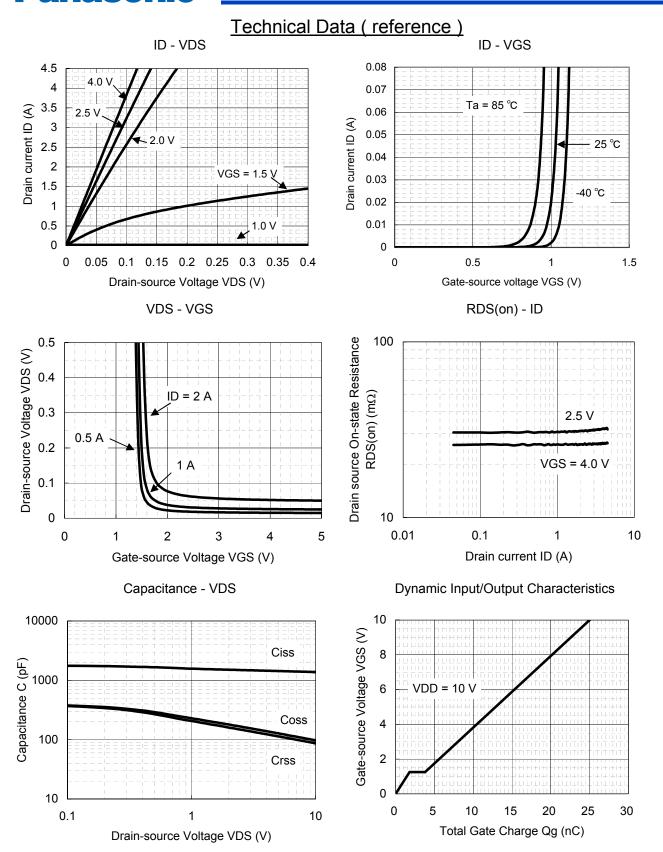
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*2 Turn-on and Turn-off test circuit



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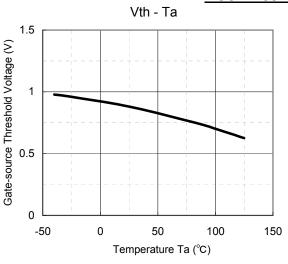


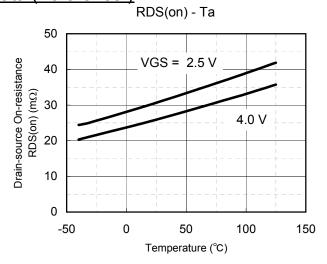
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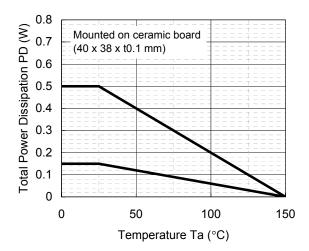
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Technical Data (reference)

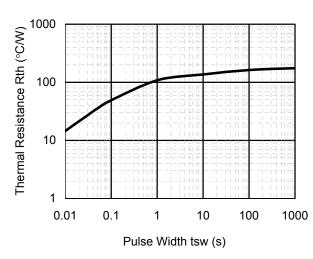


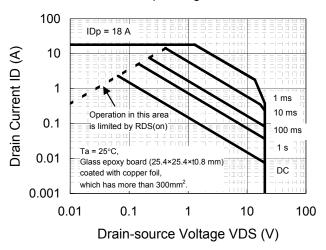






Rth - tsw Safe Operating Area

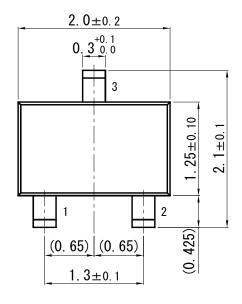


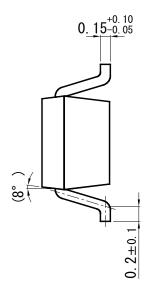


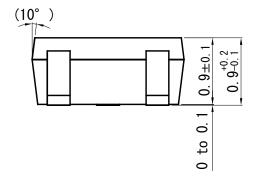
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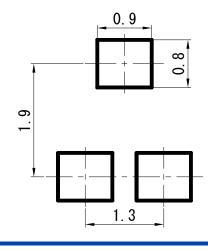
SMini3-G1-B







■ Land Pattern (Reference) (Unit : mm)



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